App. Serial No. 10/560,573 Docket No.: US030162US2

Listing of the claims:

Please amend claims 1-3 as indicated below. This listing of claims replaces all prior versions.

1. (Currently amended) A thin film Silicon on Insulator (SOI) device comprising:

a source;

a gate;

a drain;

an SOI layer;

a substrate layer; an insulator layer between the SOI layer and the substrate layer, wherein when the substrate layer is maintained at a potential sufficiently lower than a potential of the source a parasitic MOS channel is formed between the source and drain; and

a Deep N implant layer formed between either the source or drain and the <u>SOI</u> insulator layer to prevent flow of current between the source and drain via the parasitic MOS channel when the device is in an off state.

- 2. (Currently amended) The device of claim 1 wherein the Deep N implant layer is formed between the source and the <u>SOI</u> insulator layer.
- 3. (Currently amended) The device of claim 1 wherein the Deep N implant layer is formed between the drain and the <u>SOI-insulator</u> layer.

4-11 (Cancelled)

12. (*Previously presented*) The device of claim 1, wherein the substrate layer is maintained at a potential that is about 200 volts lower than the potential of the source.